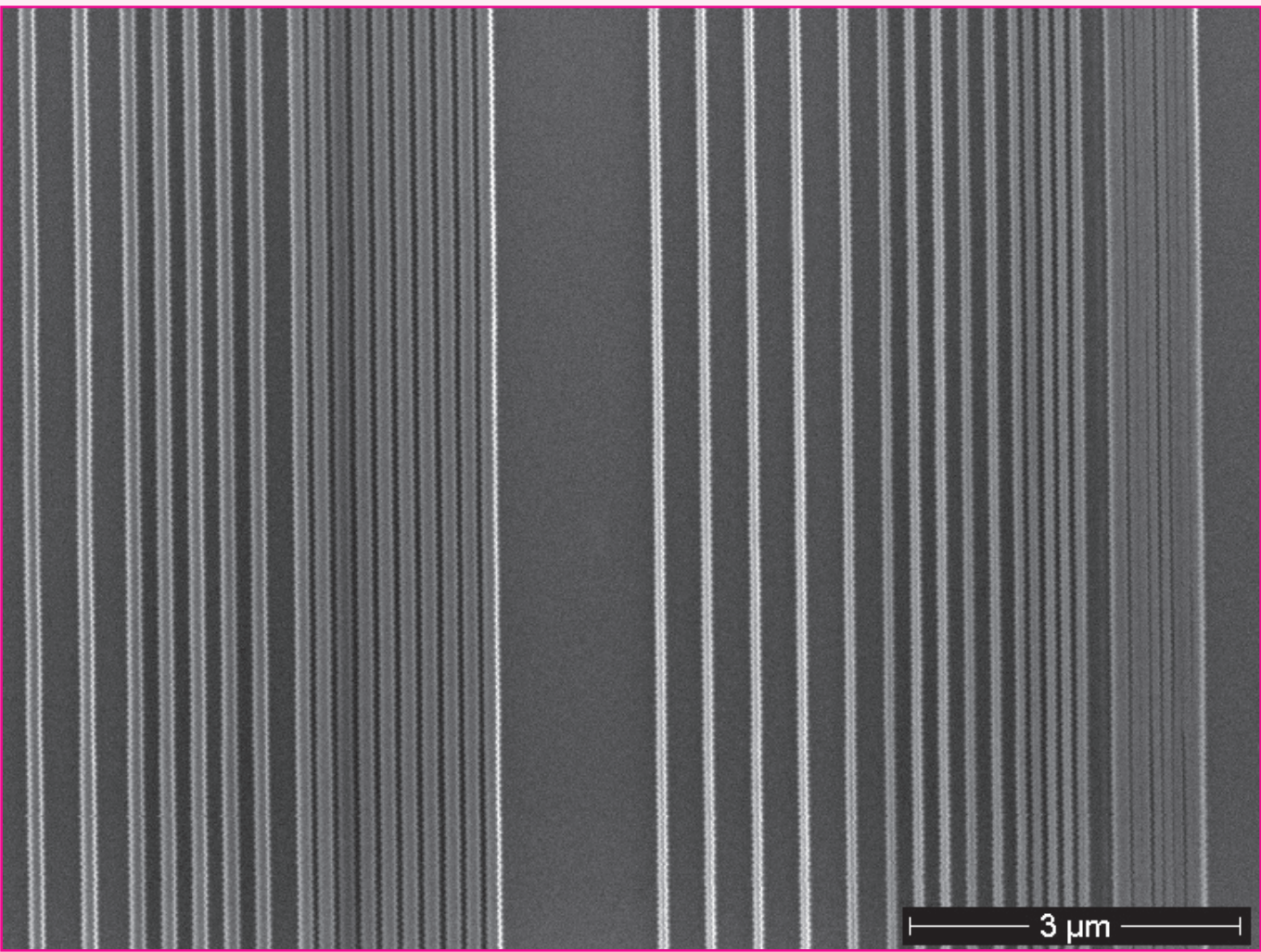
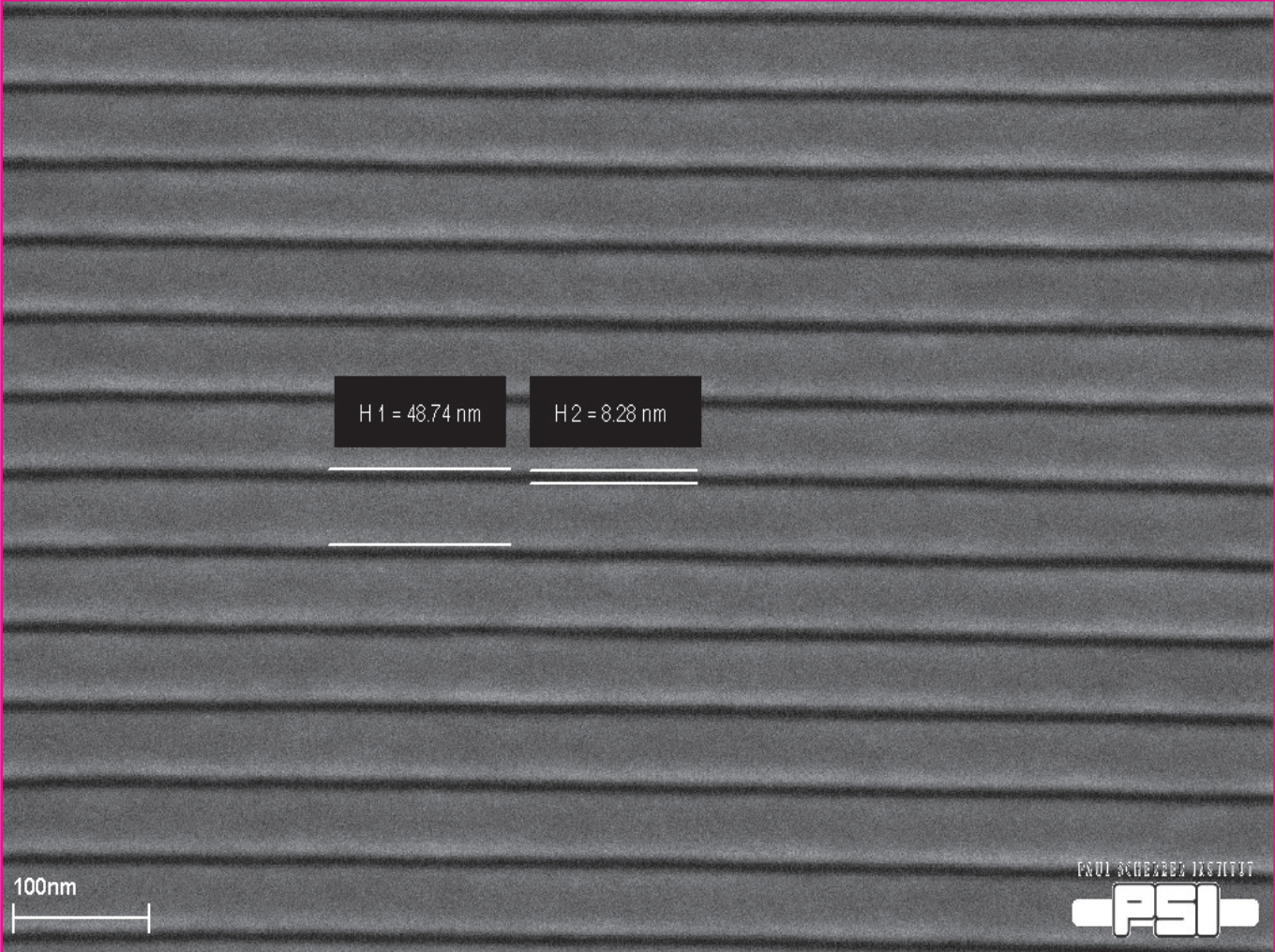


Thermoplastic Resists for Nanoimprint Lithography

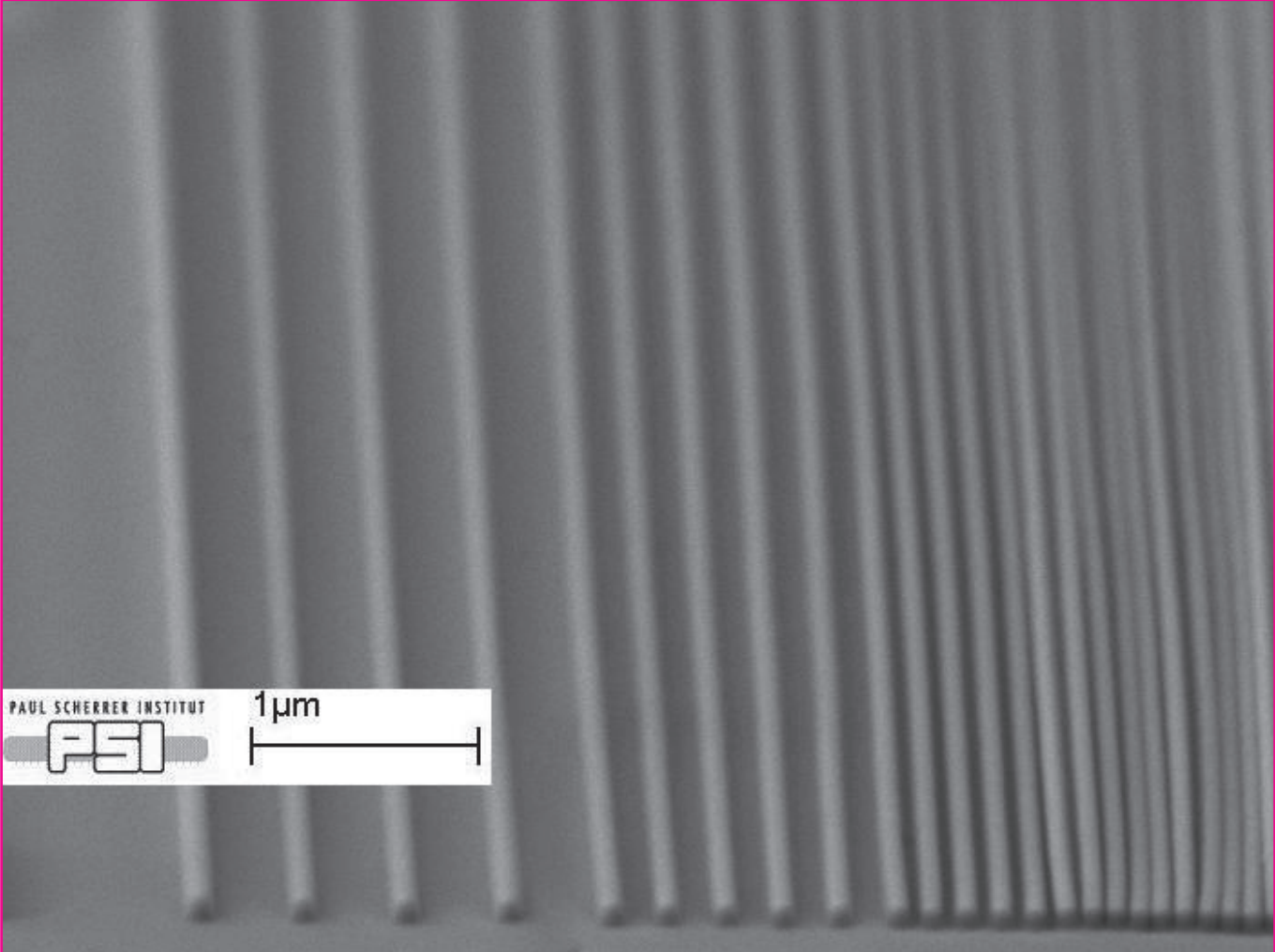
mr-I 7000R and mr-I 8000R – Thermoplastics with Built-in Release Properties



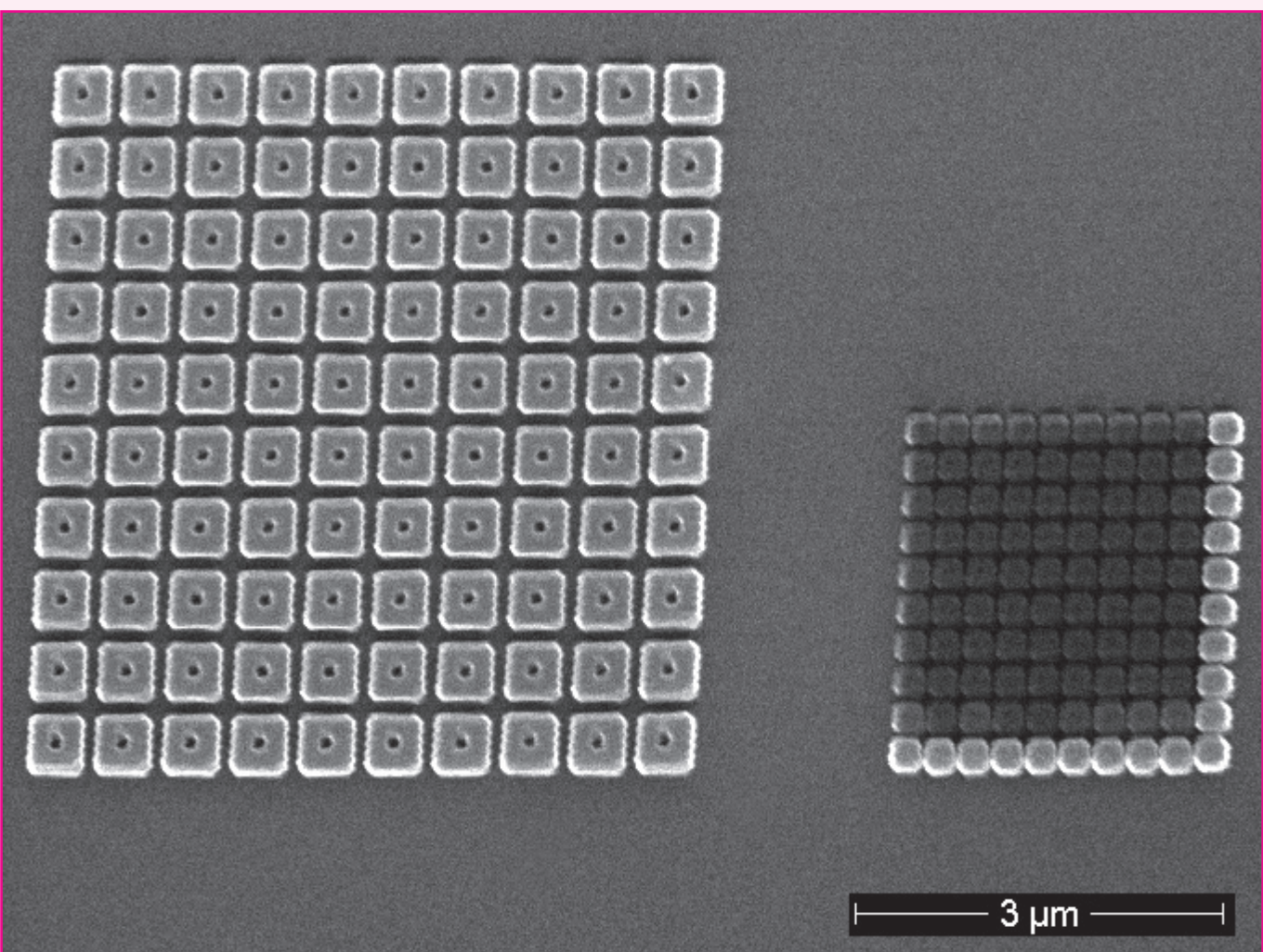
75 nm and 100 nm lines imprinted in mr-I 8030R, varying pitch



12 nm trenches, 50 nm pitch, imprinted in mr-I 7000R (Courtesy of Eulitha AG and Paul Scherrer Institute)



50 nm lines imprinted in mr-I 7030R (Courtesy of Paul Scherrer Institute)



75 nm and 100 nm squares imprinted in mr-I 7030R



mrt logo imprinted in mr-I 7030R

- Tailor-made for thermal nanoimprint lithography
- Easy stamp detachment, efficient release force reduction
- Longer life-time of anti-sticking layer on the mould

Unique Features

- Excellent properties for thermal NIL
 - Short cycle times due to fast polymer flow
 - Sub-20 nm resolution
 - Low residual layer thickness
 - Low release forces
- Longer life-time of anti-sticking layers on the stamp
- High plasma etch resistance

Applications

- Etch mask for pattern transfer
- Fabrication of nanopatterns for
 - High brightness LEDs
 - Photonic crystals
 - Patterned media
 - Nano-optical devices, sub-wavelength optical elements
 - Microfluidics, bio applications

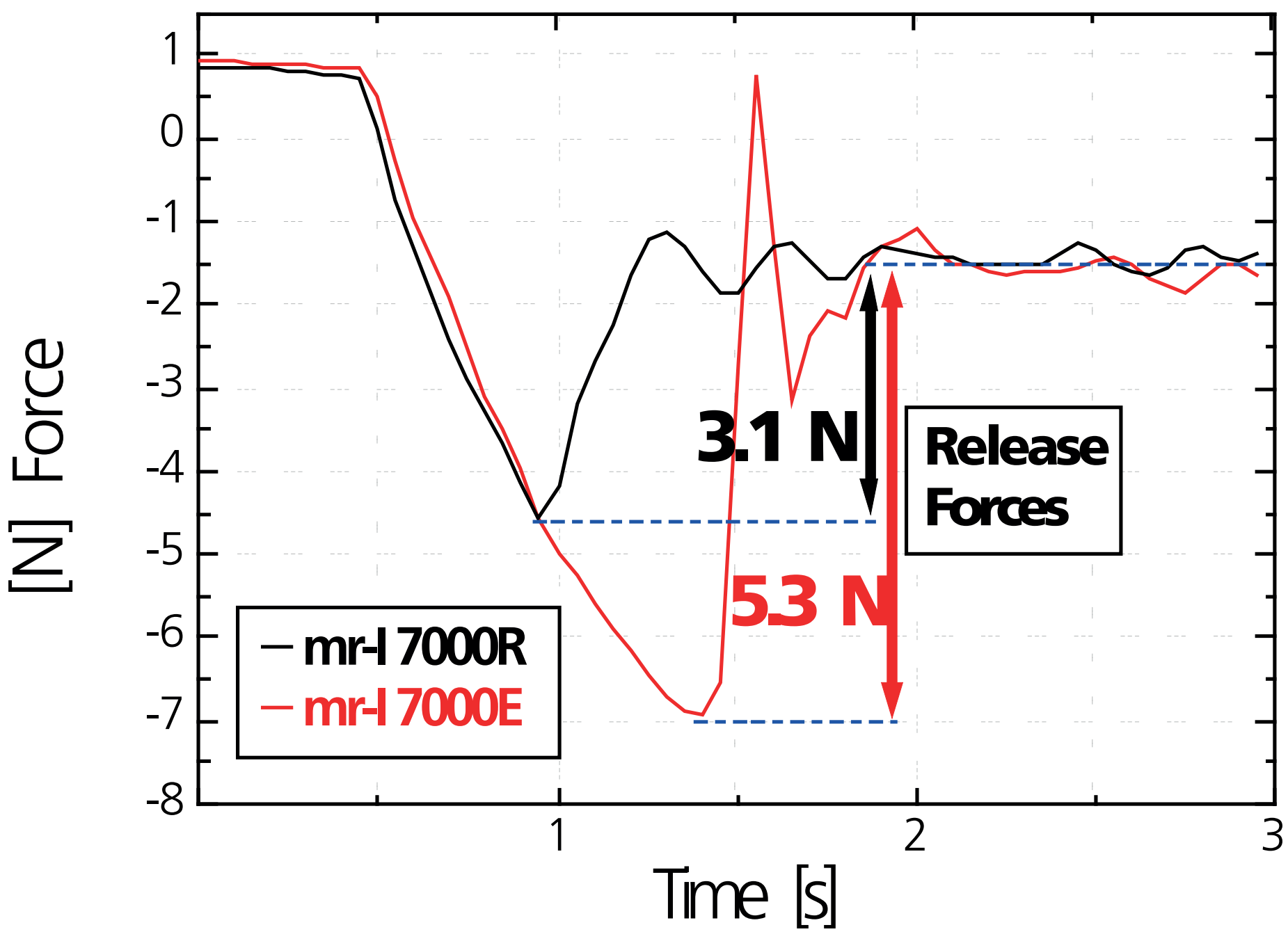
Technical Data ¹

Parameter	mr-I 7000R	mr-I 8000R
Glass transition temperature T_g	50 °C	105 °C
Imprint temperature	120 – 140 °C	150 – 180 °C
Imprint pressure	20 – 40 bar	20 – 40 bar
Ready-to-use solutions for standard film thicknesses ² (3000 rpm)	mr-I 7010R 100 nm mr-I 7020R 200 nm mr-I 7030R 300 nm	mr-I 8010R 100 nm mr-I 8020R 200 nm mr-I 8030R 300 nm

¹ Processing guidelines available on request

² Customized film thicknesses available on request

Release Force Reduction



Forces during stamp release: comparison between mr-I 7000R to its non-modified analogue mr-I 7000E

Conventional resist formulations mr-I 7000E and mr-I 8000E without fluorinated components are still available upon request in equal film thickness ranges.

Process Flow

